

Wafer Edge Defect Inspection

Abstract of the Disclosure

5 A wafer edge defect inspection method and apparatus for use in an integrated circuit fabrication system includes an image capturing device for capturing images of the edges of wafers, a database in which the images are stored and accessible for analysis and a computer for analyzing the images of one or more wafer edges to locate edge defects and for evaluating the performance of the fabrication system. The inspection and data storage are performed automatically. The database storage enables detailed analysis of many wafers and fabrication process steps.